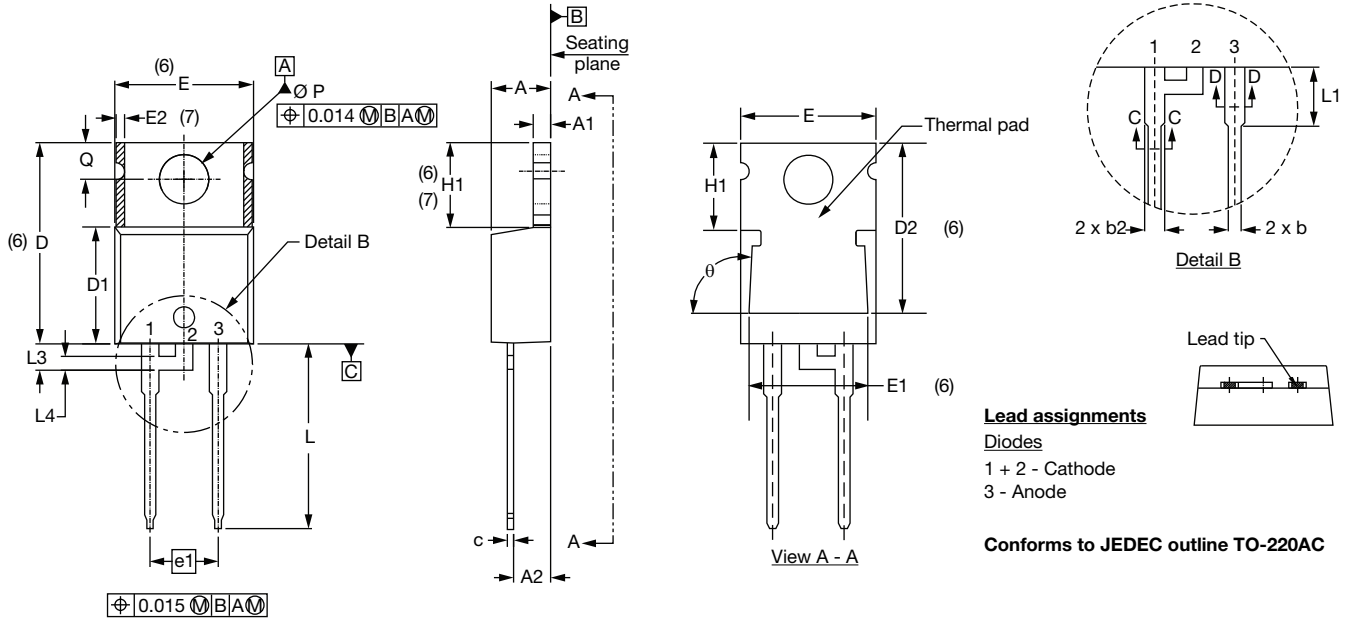


TO-220AC, TO-220AC FULL-PAK

DIMENSIONS FOR TO-220AC in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183		E	10.11	10.51	0.398	0.414	3, 6
A1	1.14	1.40	0.045	0.055		E1	6.86	8.89	0.270	0.350	6
A2	2.56	2.92	0.101	0.115		E2	-	0.76	-	0.030	7
b	0.69	1.01	0.027	0.040		e	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4	e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068		H1	6.09	6.48	0.240	0.255	6, 7
b3	1.14	1.73	0.045	0.068	4	L	13.52	14.02	0.532	0.552	
c	0.36	0.61	0.014	0.024		L1	3.32	3.82	0.131	0.150	2
c1	0.36	0.56	0.014	0.022	4	L3	1.78	2.13	0.070	0.084	
D	14.85	15.25	0.585	0.600	3	L4	0.76	1.27	0.030	0.050	2
D1	8.38	9.02	0.330	0.355		∅ P	3.54	3.73	0.139	0.147	
D2	11.68	12.88	0.460	0.507	6	Q	2.60	3.00	0.102	0.118	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline

Outline Dimensions

Vishay Semiconductors TO-220AC, TO-220AC FULL-PAK



DIMENSIONS FOR TO-220AC FULL-PAK in millimeters

